



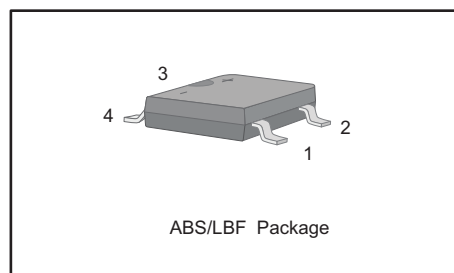
2A SURFACE MOUNT GLASS PASSIVATED BRIDGE RECTIFIER

FEATURES:

- Glass Passivated Chip Junction
- Reverse Voltage - 100 to 1000 V
- Forward Current - 2.0 A
- Fast reverse recovery time
- Designed for Surface Mount Application

PINNING

PIN	DESCRIPTION
1	Input Pin (~)
2	Input Pin (~)
3	Output Anode (+)
4	Output Cathode (-)



MECHANICAL DATA

- Case: ABS/LBF
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 88mg 0.0031oz

Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	FTB1S-20	FTB2S-20	FTB4S-20	FTB6S-20	FTB8S-20	FTB10S-20	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	100	200	400	600	800	1000	V
Average Rectified Output Current at $T_c = 115^\circ C$	I_o	2.0						A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	50						A
I^2t Rating for Fusing ($1ms \leq t < 8.3ms$)	I^2t	10.4						A ² S
Maximum Forward Voltage at 2.0 A	V_F	1.3						V
Maximum DC Reverse Current $T_a = 25^\circ C$ at Rated DC Blocking Voltage $T_a = 125^\circ C$	I_R	5.0 200						μA
Typical Junction Capacitance (Note1)	C_j	30						pF
Typical Thermal Resistance (Note2)	$R_{\theta JA}$	50						$^\circ C/W$
Maximum Reverse Recovery Time (Note3)	t_{rr}	350						ns
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150						$^\circ C$

Note: 1. Measured at 1 MHz and applied reverse voltage of 4 V D.C

2. Mounted on glass epoxy PC board with 4×1.5" × 1.5" (3.81 × 3.81 cm) copper pad.

3. Measured with $I_f = 0.5 A, I_R = 1 A, I_{rr} = 0.25 A$.



Fig.1 Average Rectified Output Current Derating Curve

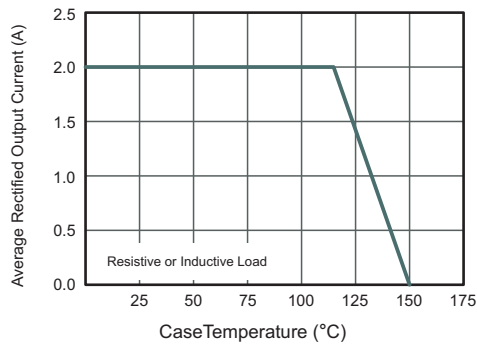


Fig.2 Typical Reverse Characteristics

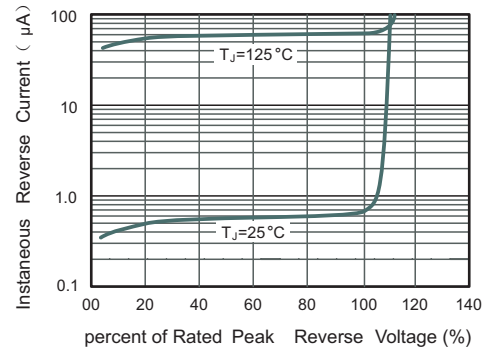


Fig.3 Typical Instantaneous Forward Characteristics

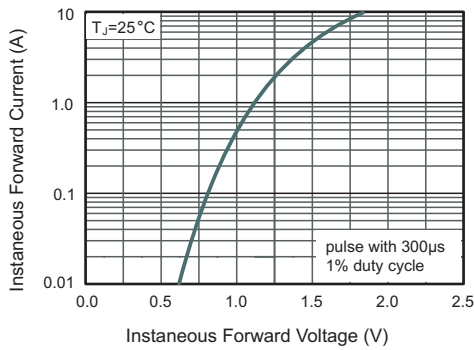


Fig.4 Typical Junction Capacitance

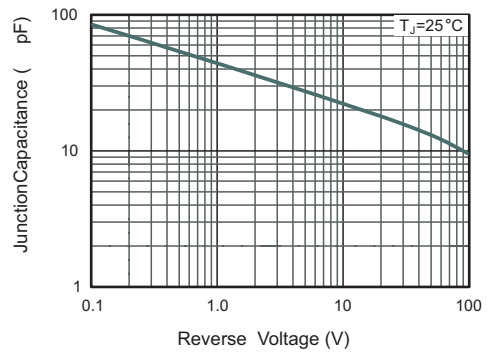
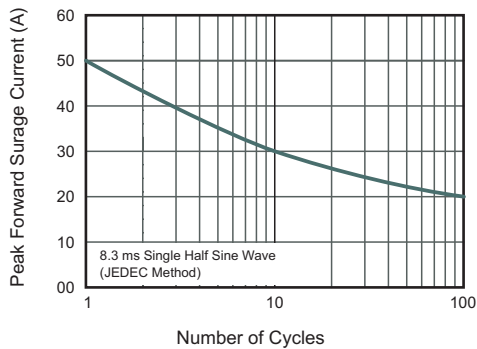


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

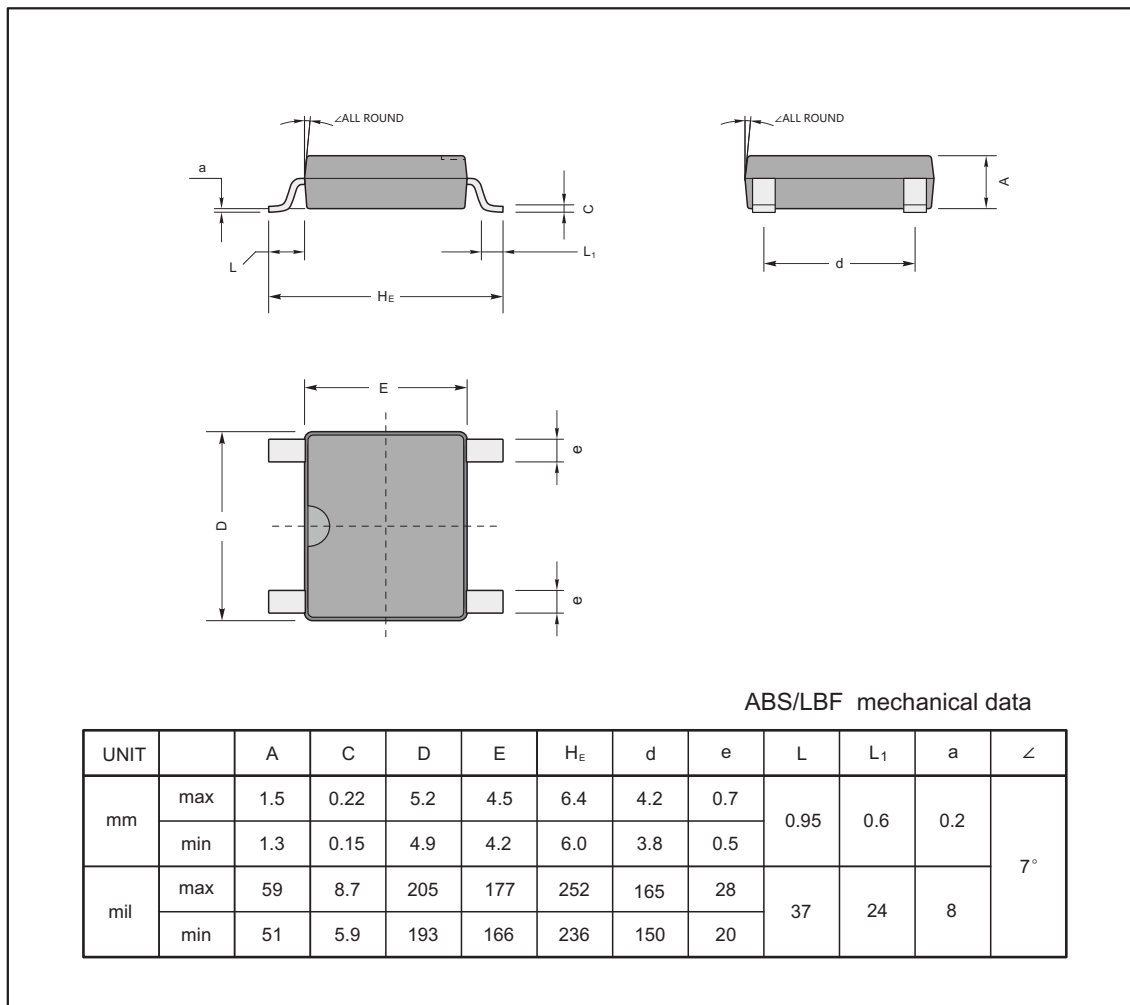




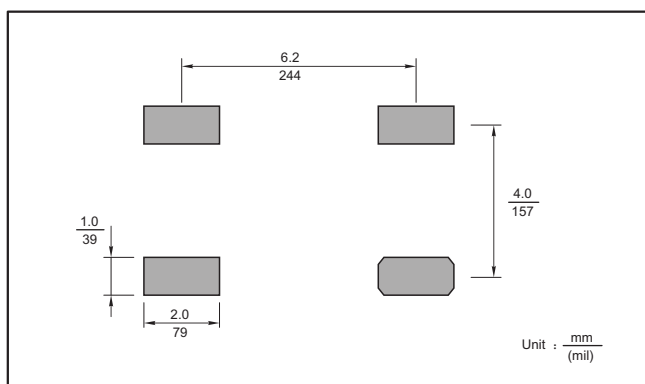
PACKAGE OUTLINE

Plastic surface mounted package; 4 leads

ABS/LBF



The recommended mounting pad size



Marking

Type number	Marking code
FTB1S-20	F20T1
FTB2S-20	F20T2
FTB4S-20	F20T4
FTB6S-20	F20T6
FTB8S-20	F20T8
FTB10S-20	F20T10



Important Notice and Disclaimer

Jingdao Microelectronics reserves the right to make changes to this document and its products and specifications at any time without notice. Customers should obtain and confirm the latest product information and specifications before final design, purchase or use.

Jingdao Microelectronics makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does Jingdao Microelectronics assume any liability for application assistance or customer product design.

Jingdao Microelectronics does not warrant or accept any liability with products which are purchased or used for any unintended or unauthorized application.

No license is granted by implication or otherwise under any intellectual property rights of Jingdao Microelectronics.

Jingdao Microelectronics products are not authorized for use as critical components in life support devices or systems without express written approval of Jingdao Microelectronics.